

<b>PCN Number:</b>	20160823001	<b>PCN Date:</b>	Sept. 2, 2016
<b>Title:</b>	Carrier Tape Change for select TSSOP Package Device		
<b>Customer Contact:</b>	<a href="#">PCN Manager</a>	<b>Dept:</b>	Quality Services
<b>Proposed 1<sup>st</sup> Ship Date:</b>	Mar. 2, 2017		
<b>Change Type:</b>			
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Assembly Process
<input type="checkbox"/>	Design	<input type="checkbox"/>	Electrical Specification
<input type="checkbox"/>	Test Site	<input checked="" type="checkbox"/>	Packing/Shipping/Labeling
<input type="checkbox"/>	Wafer Bump Site	<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>	Wafer Fab Site	<input type="checkbox"/>	Wafer Fab Materials
		<input type="checkbox"/>	Part number change
		<input type="checkbox"/>	Assembly Materials
		<input type="checkbox"/>	Mechanical Specification
		<input type="checkbox"/>	Test Process
		<input type="checkbox"/>	Wafer Bump Process
		<input type="checkbox"/>	Wafer Fab Process

### PCN Details

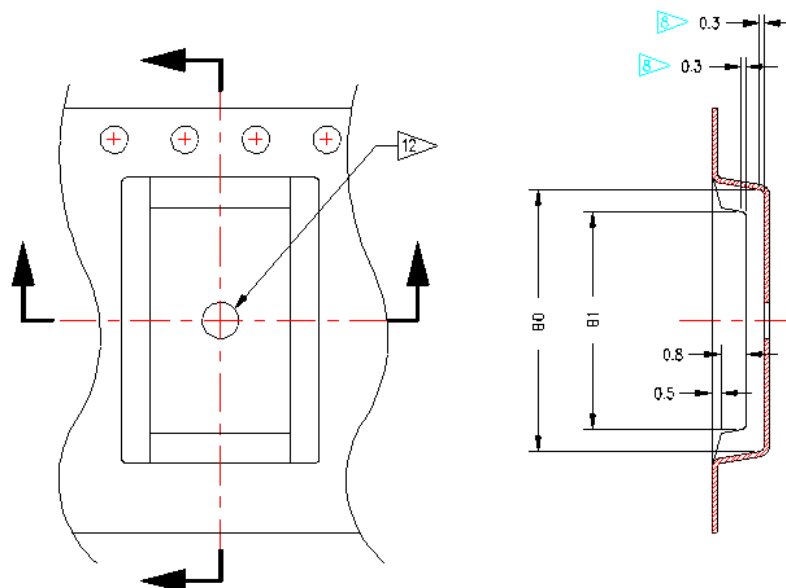
#### Description of Change:

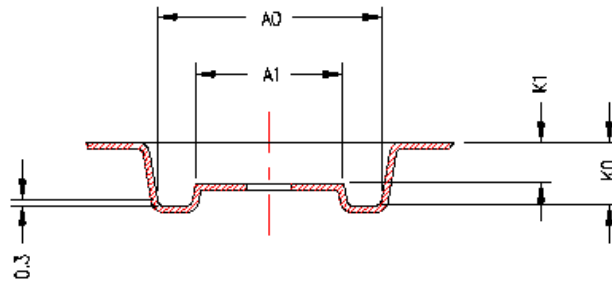
Texas Instruments is pleased to announce the qualification of a new carrier tape for select TSSOP Package Device. The material composition between the 2 carrier tapes is the same. A dimensional comparison summary is below:

#### Carrier tape Dimensions:

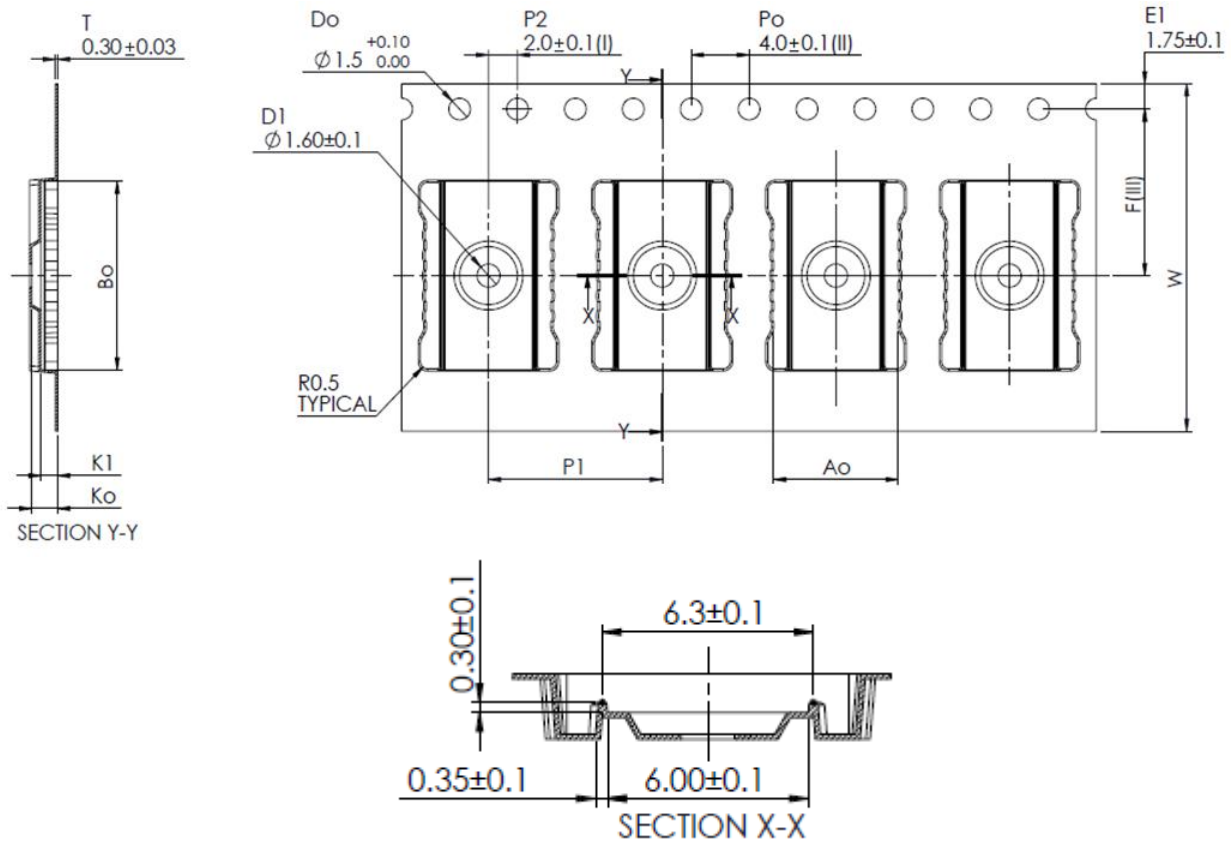
Dimension	From	To
Part No.	4068850-0015	<b>4212589-0040</b>
A0	8.60 (+/- 0.1) mm	8.60 (+/- 0.1) mm
B0	15.80 (+/- 0.1) mm	<b>13.00 (+/- 0.1) mm</b>
K0	1.80 (+/- 0.1) mm	1.80 (+/- 0.1) mm
K1	1.30 (+/- 0.1) mm	<b>1.15 (+/- 0.1) mm</b>
W	24.00 (+/- 0.3) mm	24.00 (+/- 0.3) mm

#### Current Design:





**Proposed Design:**



**Reason for Change:**

Quality Improvement

**Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):**

None

**Changes to product identification resulting from this PCN:**

New Carrier Tape design

**Product Affected:**

8W244AMDGGREP4	CLVTH162245IDGGREP	V62/04601-03YE	V62/05612-01YE
CALVC164245IDGGREP	CLVTH16244AMDGGREP	V62/04602-01YE	V62/05612-02YE
CALVC164245MDGGREP	CLVTH16244AQDGGREP	V62/04708-01XE	V62/09605-01XE
CAVCB164245MDGGREP	CLVTH16245AQDGGREP	V62/04709-01XE	V62/12667-01XE
CLVC16244AIDGGREP	CLVTH16373IDGGREP	V62/04712-01XE	V62/13602-01XE
CLVC16T245MDGGREP	CVMEH22501AIDGGREP	V62/04724-01XE	
CLVCH16T245MDGGREP	CVMEH22501AMDGGREP	V62/05606-01XE	
CLVTH162244IDGGREP	V62/04601-01YE	V62/05606-02XE	

# Qualification Report



Revision: K

EQ# :  
A/T Site: T1M 1560

## Lead Package Carrier Tape Qualification Summary

Reference (QSS 003-008, 009-006, 014-102, 007-102)

<b>Supplier:</b>	<u>C-PAK</u>	
<b>Vendor Part No:</b>	<u>NA</u>	
<b>TI Part No:</b>	<u>4212589-0040</u>	(if available)
<b>Weight/meter (g):</b>	<u>NA</u>	
<b>Material:</b>	<u>POLYSTYRENE</u>	
<b>Package Description</b>	<u>DGG 48</u>	(yes/no)
<b>Package Designator:</b>	<u>DGG 48</u>	
<b>Result:</b>	<u>PASS</u>	
<b>Date:</b>	<u>18th June 2016</u>	

<b>I. First Article Inspection Test</b>	<u>PASS</u>	(Pass/Fail)
<b>II. Manufacturability Test</b>	<u>PASS</u>	
<b>III. Dimensional Test</b>	<u>PASS</u>	
<b>IV. Camber Test</b>	<u>PASS</u>	
<b>V. Surface Resistivity Test</b>	<u>PASS</u>	
<b>VI. Fit Analysis</b>	<u>PASS</u>	
<b>VII. Drop Test</b>	<u>PASS</u>	

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	<a href="mailto:PCNAmericasContact@list.ti.com">PCNAmericasContact@list.ti.com</a>
Europe	<a href="mailto:PCNEuropeContact@list.ti.com">PCNEuropeContact@list.ti.com</a>
Asia Pacific	<a href="mailto:PCNAsiaContact@list.ti.com">PCNAsiaContact@list.ti.com</a>
Japan	<a href="mailto:PCNJapanContact@list.ti.com">PCNJapanContact@list.ti.com</a>